

Di Xu

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/10723275/publications.pdf>

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7
papers

273
citations

1684188

5
h-index

1720034

7
g-index

9
all docs

9
docs citations

9
times ranked

238
citing authors

#	ARTICLE	IF	CITATIONS
1	Nanotwin formation in copper thin films by stress/strain relaxation in pulse electrodeposition. Applied Physics Letters, 2007, 91, .	3.3	80
2	<i>In situ</i> measurements of stress evolution for nanotwin formation during pulse electrodeposition of copper. Journal of Applied Physics, 2009, 105, .	2.5	71
3	Structure and migration of (112) step on (111) twin boundaries in nanocrystalline copper. Journal of Applied Physics, 2008, 104, .	2.5	57
4	Nanotwin formation and its physical properties and effect on reliability of copper interconnects. Microelectronic Engineering, 2008, 85, 2155-2158.	2.4	27
5	Modulation of Crystallographic Texture and Twinning Structure of Cu Nanowires by Electrodeposition. Journal of the Electrochemical Society, 2013, 160, D207-D211.	2.9	24
6	Electromigration failure with thermal gradient effect in SnAgCu solder joints with various UBM. , 2009, , .		10
7	Nanotwin-modified copper interconnects and its effect on the physical properties of copper. , 2009, , .		0